



SOT274-2

plastic shrink dual in-line package; 64 leads (750 mil); face down

16 October 2018

Package information

1 Package summary

| | |
|---------------------------------------|------------------------------------|
| Terminal position code | D (double) |
| Package type descriptive code | SDIP64 |
| Package type industry code | SDIP64 |
| Package style descriptive code | SDIP (shrink dual in-line package) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MS-021 |
| Mounting method type | T (through-hole mount) |
| Issue date | 24-02-2006 |
| Manufacturer package code | SOT274 |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|------|--------|-------|------|
| package length | 57.7 | 58.185 | 58.67 | mm |
| package width | 16.9 | 17.05 | 17.2 | mm |
| seated height | - | 5.84 | - | mm |
| package height | - | 4.57 | - | mm |
| nominal pitch | - | 1.778 | - | mm |
| actual quantity of termination | - | 64 | - | |



2 Package outline

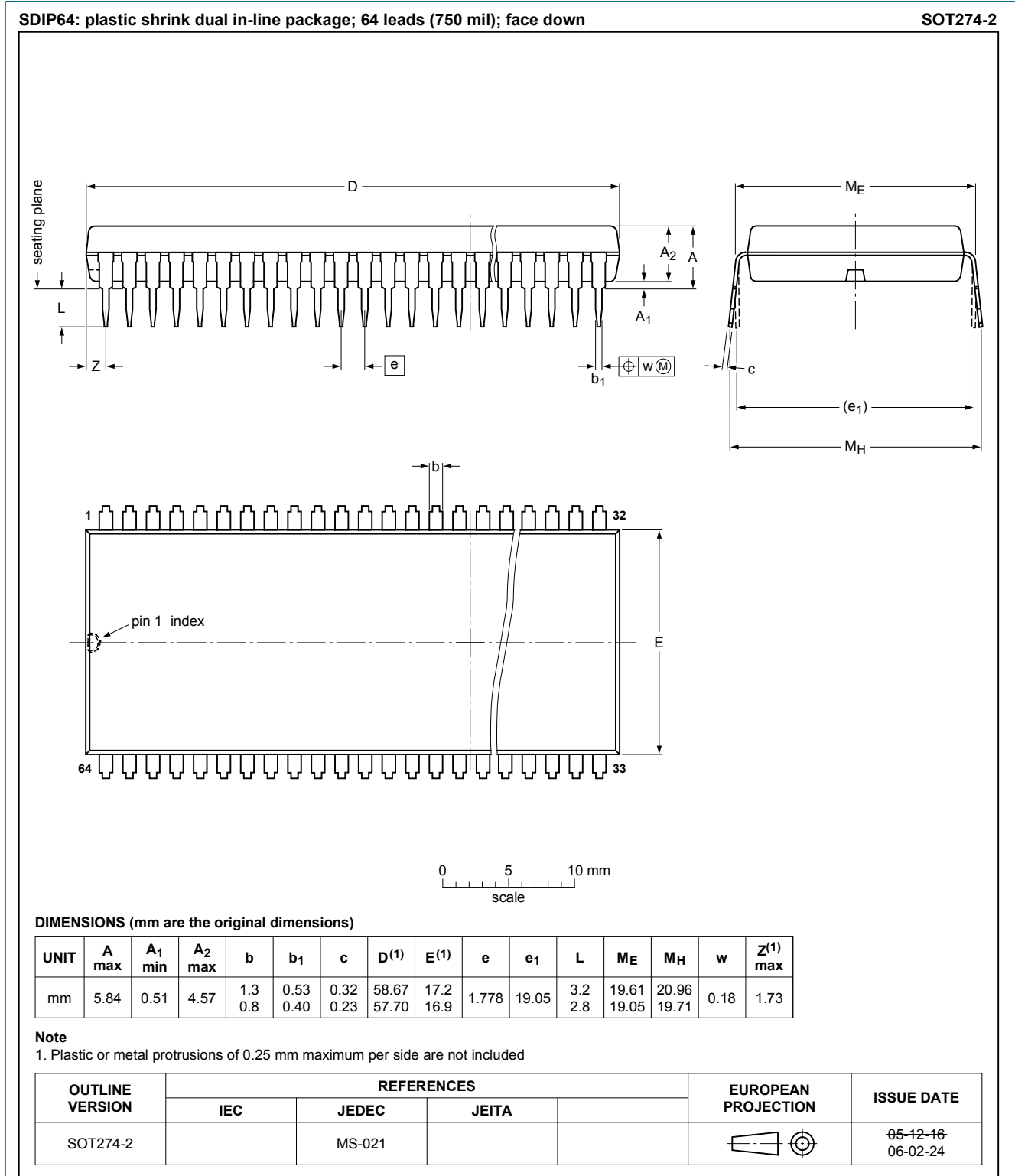


Figure 1. Package outline SDIP64 (SOT274-2)

3 Legal information

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